

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

30.03.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	A00 B00
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	214		2	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3	
		70	L2		
C-RaS-FR4-DS-0.991mm-070+070-TG150-HF...	50203142	850		4	
		70	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	214		5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	7	

Thickness after Pressing

B00: 1440 µm Tol+: 155 µm Tol-: 155 µm Dmax: 1595 µm Dmin: 1285 µm

Thickness over all

0 µm Tol+: 0 µm Tol-: 0 µm Dmax: 0 µm Dmin: 0 µm

Demand for customer

Thickness (D): 1550 µm Tol+: 155 µm Tol-: 155 µm Dmax: 1705 µm Dmin: 1395 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 1454 µm

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